

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

Claim 1. (currently amended): A heat sensitive recording material comprising a heat sensitive color-forming layer disposed on a support, the layer having an electron donating colorless dye and an electron accepting compound, wherein at least one type of the electron accepting compound is 2,4-bis(phenylsulfonyl) phenol, and the heat sensitive color-forming layer further has 2-naphthylbenzyl ether and an amide compound as thermally fusible substances, wherein the amide compound is selected from the group consisting of behenic acid amide, hydroxystearic acid amide, methylolstearic acid amide, methylolbehenic acid amide, methylenebisstearic acid amide, ethylenebisstearic acid amide, and ethylenebisbehenic acid amide, and the amount of amide compound does not exceed the amount of 2-naphthylbenzyl ether.

Claims 2 and 3 (canceled).

Claim 4. (original): The heat sensitive recording material of claim 1, wherein the amide compound is methylolstearic acid amide.

Claim 5. (original): The heat sensitive recording material of claim 1, wherein the amide compound is ethylenebisstearic acid amide.

Claim 6. (original): The heat sensitive recording material of claim 1, wherein the content of the amide compound is 2 to 100 parts by mass with respect to 100 parts by mass of 2-naphthylbenzyl ether.

Claim 7. (original): The heat sensitive recording material of claim 1, wherein the content of 2,4-bis(phenylsulfonyl) phenol is no less than 50% by mass of the total amount of the electron accepting compound.

Claim 8. (original): The heat sensitive recording material of claim 1, wherein the electron accepting compound has a volume average particle diameter of 0.5 to 1.5 μm .

Claim 9. (original): The heat sensitive recording material of claim 1, wherein the total amount of the thermally fusible substances is 75 to 200 parts by mass with respect to 100 parts by mass of the electron accepting compound.